

## P-Channel Enhancement Mode Power MOSFET

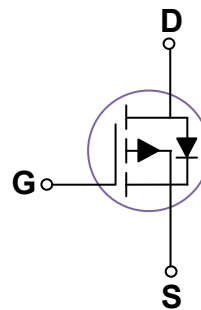
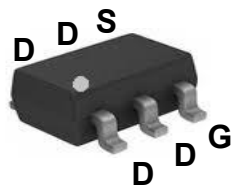
### General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### Features

$V_{DS}$	-30V
$I_D$ (at $V_{GS}=-10V$ )	-6A
$R_{DS(ON)}$ (at $V_{GS}=-10V$ )	30mΩ(Max)
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$ )	45mΩ(Max)

### SOT23-6



### Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units	
Drain-Source Voltage	$V_{DS}$	-30	V	
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V	
Drain Current-Continuous	TC=25°C	$I_D$	-6.0	A
	TC=100°C	$I_D$	-3.6	A
Drain Current – Pulsed	$I_{DM}$	-24	A	
Maximum Power Dissipation	$P_D$	1.56	W	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C	

### Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance junction-case	$R_{\theta Jc}$		1.1	°C /W
Thermal Resistance unction-to-Ambient	$R_{\theta JA}$		60	°C /W

**Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>STATIC PARAMETERS</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V			1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.5	-1.0	-1.5	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-4.0A		25	30	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2.0A		35	45	mΩ
<b>DYNAMIC PARAMETERS</b>						
C <sub>ISS</sub>	Input Capacitance	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, F=1.0MHz		757		pF
C <sub>OSS</sub>	Output Capacitance			122		pF
C <sub>RSS</sub>	Reverse Transfer Capacitance			88		pF
<b>SWITCHING PARAMETERS</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =-15V, I <sub>D</sub> =-1A, V <sub>GS</sub> =-10V, R <sub>G</sub> =3Ω		4.6		nS
t <sub>r</sub>	Turn-on Rise Time			14		nS
t <sub>d(off)</sub>	Turn-Off Delay Time			34		nS
t <sub>f</sub>	Turn-Off Fall Time			18		nS
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-15V, I <sub>D</sub> =-5A, V <sub>GS</sub> =-4.5V		8		nC
Q <sub>gs</sub>	Gate-Source Charge			3.3		nC
Q <sub>gd</sub>	Gate-Drain Charge			2.3		nC
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>SD</sub> =-1A		0.72	1.4	V

**Note:**

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≅ 300us , duty cycle ≅ 2%.
3. Essentially independent of operating temperature.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

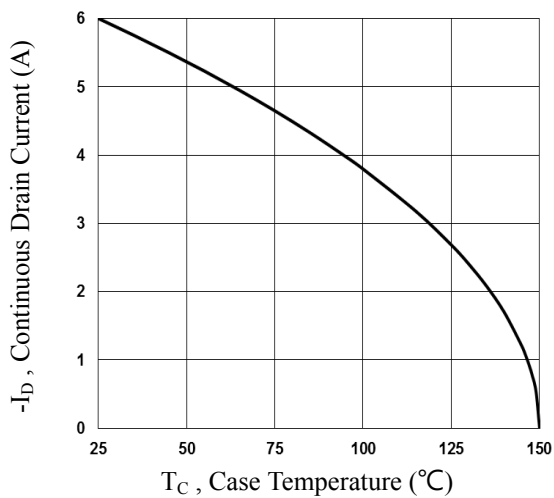


Fig.1 Continuous Drain Current vs.  $T_C$

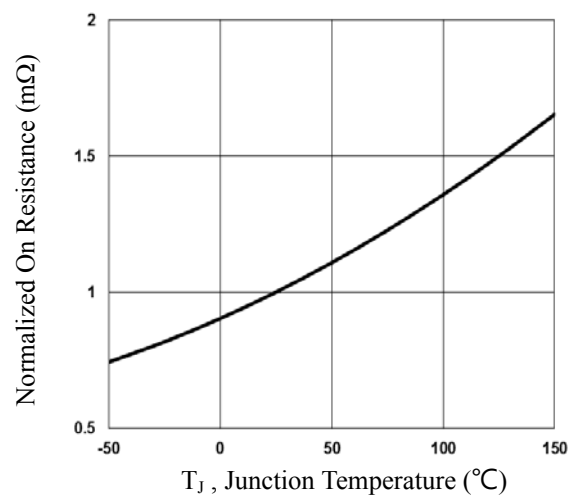


Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$

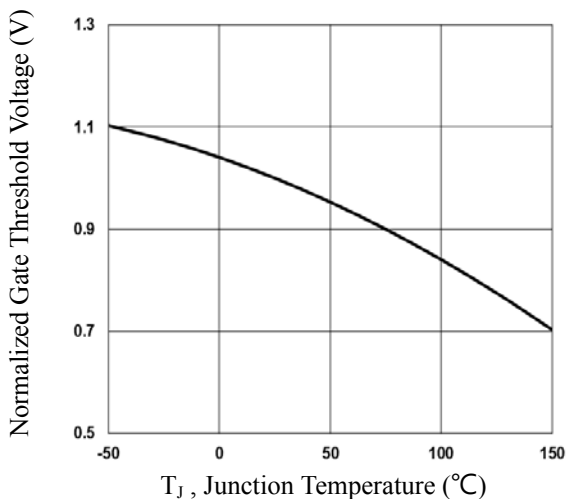


Fig.3 Normalized  $V_{th}$  vs.  $T_J$

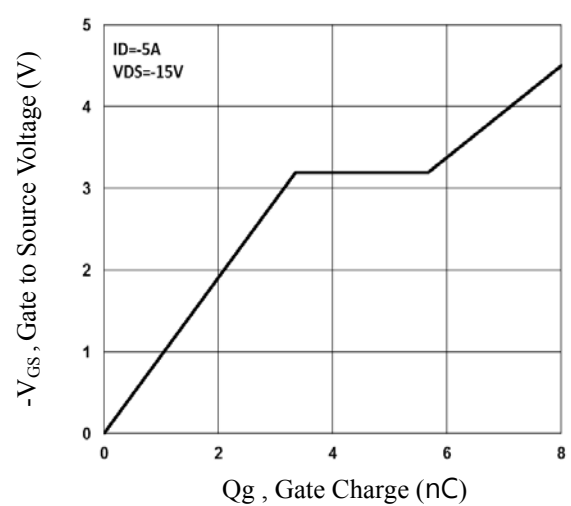


Fig.4 Gate Charge Waveform

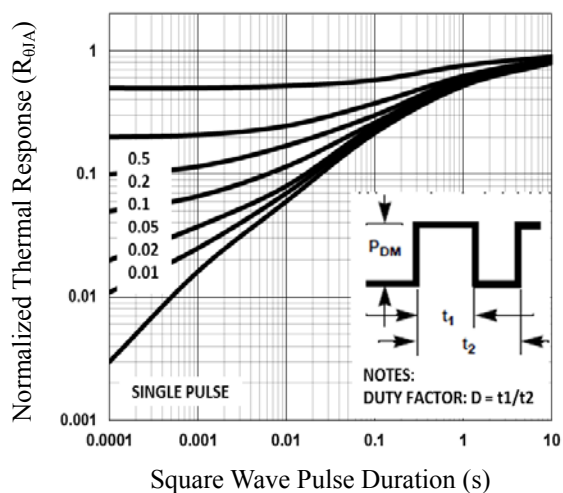


Fig.5 Normalized Transient Impedance

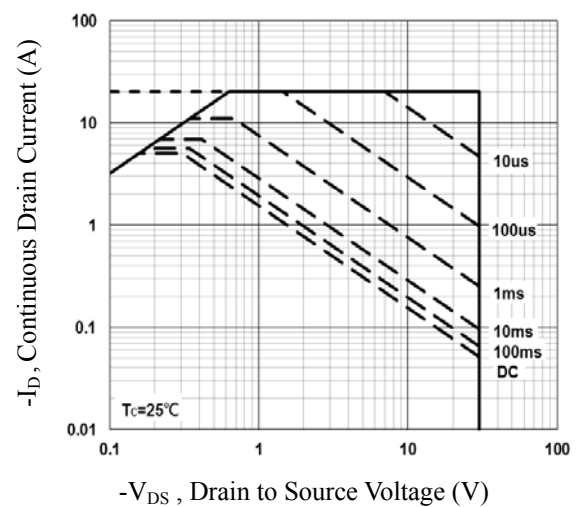


Fig.6 Maximum Safe Operation Area

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

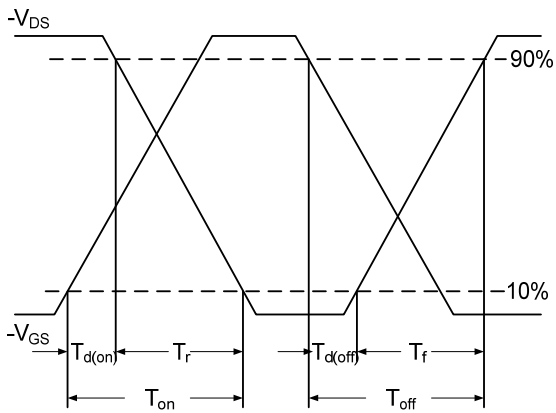


Fig.7 Switching Time Waveform

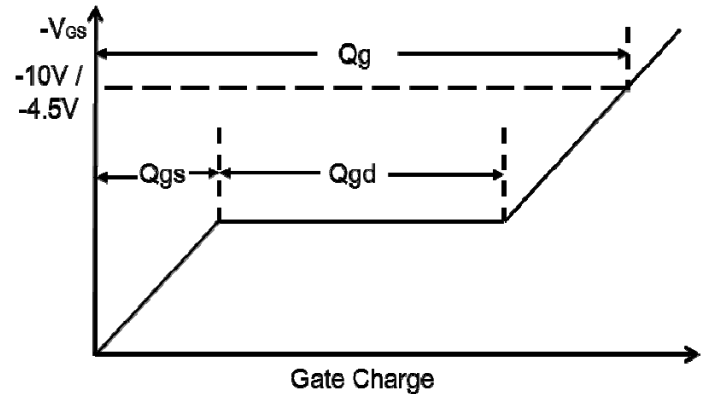
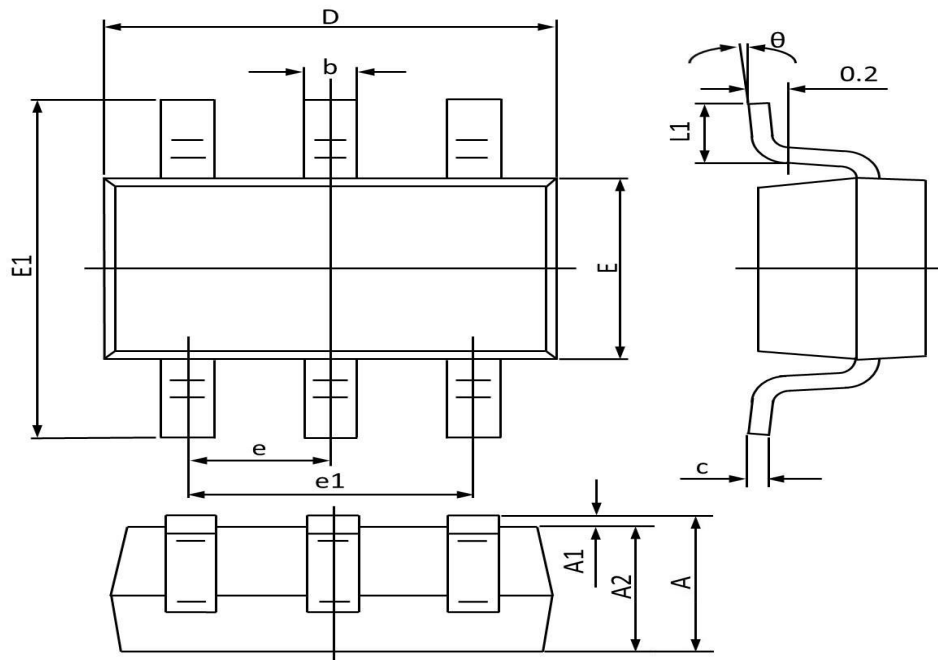


Fig.8 Gate Charge Waveform

## SOT23-6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.450	-	0.057	-
A1	0.100	0.000	0.004	0.000
A2	1.300	1.050	0.051	0.041
b	0.500	0.300	0.020	0.012
c	0.200	0.100	0.008	0.004
D	3.100	2.700	0.122	0.106
E	1.800	1.400	0.071	0.055
E1	3.000	2.600	0.118	0.102
e	0.95BSC		0.037BSC	
e1	2.000	1.800	0.079	0.071
L1	0.600	0.300	0.024	0.012
θ	10°	0°	10°	0°